

Rui Huang

List of Publications by Year in descending order

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166
papers

11,404
citations

28190

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h-index

30010

103
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167
all docs

167
docs citations

167
times ranked

10905
citing authors

#	ARTICLE	IF	CITATIONS
1	Rate dependent fracture along a silicon/epoxy interface under mixed-mode loading conditions. International Journal of Solids and Structures, 2022, 257, 111129.	1.3	12
2	Peeling and sliding of graphene nanoribbons with periodic van der Waals interactions. Journal of the Mechanics and Physics of Solids, 2022, 158, 104698.	2.3	18
3	Rate-dependent wrinkling and subsequent bifurcations of an elastic thin film on a viscoelastic layer. International Journal of Solids and Structures, 2022, 257, 111592.	1.3	7
4	Nanostructured block copolymer muscles. Nature Nanotechnology, 2022, 17, 752-758.	15.6	53
5	Analytical and finite element study on warpage and stress of 2.5D chip-package structures. , 2021, , .		0
6	A multiscale cohesive zone model for rate-dependent fracture of interfaces. Journal of the Mechanics and Physics of Solids, 2020, 145, 104142.	2.3	30
7	Mechanics at the interfaces of 2D materials: Challenges and opportunities. Current Opinion in Solid State and Materials Science, 2020, 24, 100837.	5.6	61
8	Bending with slip. Nature Materials, 2020, 19, 259-260.	13.3	8
9	The effect of moisture on the nonlinearly viscoelastic behavior of an epoxy. Mechanics of Time-Dependent Materials, 2020, 24, 435-461.	2.3	2
10	Poroelastic effects on steady state crack growth in polymer gels under plane stress. Mechanics of Materials, 2020, 143, 103320.	1.7	8
11	Linear and nonlinear poroelastic analysis of swelling and drying behavior of gelatin-based hydrogels. International Journal of Solids and Structures, 2020, 195, 43-56.	1.3	8
12	Poroelastic Effects on the Time- and Rate-Dependent Fracture of Polymer Gels. Journal of Applied Mechanics, Transactions ASME, 2020, 87, .	1.1	12
13	Phonon interaction with ripples and defects in thin layered molybdenum disulfide. Applied Physics Letters, 2019, 114, .	1.5	10
14	Rate-Dependent Decohesion Modes in Graphene-Sandwiched Interfaces. Advanced Materials Interfaces, 2019, 6, 1901217.	1.9	13
15	Bending of Multilayer van der Waals Materials. Physical Review Letters, 2019, 123, 116101.	2.9	139
16	Rate-dependent traction-separation relations for a silicon/epoxy interface informed by experiments and bond rupture kinetics. Journal of the Mechanics and Physics of Solids, 2019, 131, 1-19.	2.3	23
17	Analytical Electromechanical Modeling of Nanoscale Flexoelectric Energy Harvesting. Applied Sciences (Switzerland), 2019, 9, 2273.	1.3	10
18	Simultaneous extraction of tensile and shear interactions at interfaces. Journal of the Mechanics and Physics of Solids, 2019, 125, 225-254.	2.3	22

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19	Steady-state crack growth in polymer gels: A linear poroelastic analysis. <i>Journal of the Mechanics and Physics of Solids</i> , 2018, 118, 15-39.	2.3	29
20	Mechanics of spontaneously formed nanoblister trapped by transferred 2D crystals. <i>Proceedings of the National Academy of Sciences of the United States of America</i> , 2018, 115, 7884-7889.	3.3	130
21	A Linear Poroelastic Analysis of Time-Dependent Crack-Tip Fields in Polymer Gels. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2018, 85, .	1.1	12
22	Direct and Simultaneous Extraction of Mixed-Mode Traction-Separation Relations. <i>Conference Proceedings of the Society for Experimental Mechanics</i> , 2018, , 79-84.	0.3	0
23	Characterizing Traction-Separation Relations of TSV/SI Interfaces by Nanoindentation. <i>Conference Proceedings of the Society for Experimental Mechanics</i> , 2018, , 41-46.	0.3	0
24	Onset of swell-induced surface instability of hydrogel layers with depth-wise graded material properties. <i>Mechanics of Materials</i> , 2017, 105, 138-147.	1.7	17
25	A review on mechanics and mechanical properties of 2D materials—Graphene and beyond. <i>Extreme Mechanics Letters</i> , 2017, 13, 42-77.	2.0	920
26	Salt-Induced Swelling and Volume Phase Transition of Polyelectrolyte Gels. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2017, 84, .	1.1	27
27	Characterizing Interfacial Sliding of Through-Silicon-Via by Nano-Indentation. <i>IEEE Transactions on Device and Materials Reliability</i> , 2017, 17, 355-363.	1.5	25
28	Cavitation of water by volume-controlled stretching. <i>Extreme Mechanics Letters</i> , 2017, 11, 59-67.	2.0	11
29	Thermal fluctuations and effective bending stiffness of elastic thin sheets and graphene: A nonlinear analysis. <i>Journal of the Mechanics and Physics of Solids</i> , 2017, 107, 294-319.	2.3	49
30	Measuring Interlayer Shear Stress in Bilayer Graphene. <i>Physical Review Letters</i> , 2017, 119, 036101.	2.9	155
31	Electromechanical coupling in piezoelectric nanobeams due to the flexoelectric effect. <i>Smart Materials and Structures</i> , 2017, 26, 095025.	1.8	37
32	On determining mixed-mode traction–separation relations for interfaces. <i>International Journal of Fracture</i> , 2016, 202, 1-19.	1.1	44
33	Snap Transitions of Pressurized Graphene Blisters. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2016, 83, .	1.1	13
34	Entropic effects of thermal rippling on van der Waals interactions between monolayer graphene and a rigid substrate. <i>Journal of Applied Physics</i> , 2016, 119, .	1.1	18
35	Cracking of Polycrystalline Graphene on Copper under Tension. <i>ACS Nano</i> , 2016, 10, 9616-9625.	7.3	53
36	Processing Effect on Via Extrusion for TSVs in Three-Dimensional Interconnects: A Comparative Study. <i>IEEE Transactions on Device and Materials Reliability</i> , 2016, 16, 465-469.	1.5	7

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37	Mixed-mode traction-separation relations between graphene and copper by blister tests. International Journal of Solids and Structures, 2016, 84, 147-159.	1.3	39
38	Effect of Solvent Diffusion on Crack-Tip Fields and Driving Force for Fracture of Hydrogels. Journal of Applied Mechanics, Transactions ASME, 2015, 82, .	1.1	55
39	Investigation of thermo-mechanical stresses and reliability of 3D die-stack structures by synchrotron x-ray micro-diffraction. , 2015, , .		1
40	Selective Mechanical Transfer of Graphene from Seed Copper Foil Using Rate Effects. ACS Nano, 2015, 9, 1325-1335.	7.3	104
41	Through-silicon via stress characteristics and reliability impact on 3D integrated circuits. MRS Bulletin, 2015, 40, 248-256.	1.7	50
42	Mixed-Mode Interactions Between Graphene and Substrates by Blister Tests. Journal of Applied Mechanics, Transactions ASME, 2015, 82, .	1.1	25
43	A nonlinear, transient finite element method for coupled solvent diffusion and large deformation of hydrogels. Journal of the Mechanics and Physics of Solids, 2015, 79, 21-43.	2.3	102
44	Wet adhesion of graphene. Extreme Mechanics Letters, 2015, 3, 130-140.	2.0	16
45	Effect of Cu grain boundary sliding on TSV extrusion. , 2015, , .		2
46	Wrinkling and folding of thin films by viscous stress. Soft Matter, 2015, 11, 1814-1827.	1.2	19
47	Impact of Grain Structure and Material Properties on Via Extrusion in 3D Interconnects. Journal of Microelectronics and Electronic Packaging, 2015, 12, 118-122.	0.8	8
48	A State Space Method for Surface Instability of Elastic Layers With Material Properties Varying in Thickness Direction. Journal of Applied Mechanics, Transactions ASME, 2014, 81, .	1.1	21
49	Characterization of thermal stresses and plasticity in through-silicon via structures for three-dimensional integration. AIP Conference Proceedings, 2014, , .	0.3	4
50	Thermomechanical characterization and modeling for TSV structures. , 2014, , .		2
51	Effect of microstructure on via extrusion profile and reliability implication for copper through-silicon vias (TSVs) structures. , 2014, , .		3
52	Study of Stresses and Plasticity in Through-Silicon Via Structures for 3D Interconnects by X-Ray Micro-Beam Diffraction. IEEE Transactions on Device and Materials Reliability, 2014, 14, 698-703.	1.5	15
53	Ultra Long-Range Interactions between Large Area Graphene and Silicon. ACS Nano, 2014, 8, 11234-11242.	7.3	75
54	Interfacial Sliding and Buckling of Monolayer Graphene on a Stretchable Substrate. Advanced Functional Materials, 2014, 24, 396-402.	7.8	229

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55	A kinetic decomposition process for air-gap interconnects and induced deformation instability of a low-k dielectric cap layer. Journal of Mechanical Science and Technology, 2014, 28, 255-261.	0.7	3
56	Effect of high temperature storage on the stress and reliability of 3D stacked chip. , 2014, , .		4
57	Material characterization and failure analysis of through-silicon vias. , 2014, , .		5
58	Thermomechanical Failure Analysis of Through-Silicon Via Interface Using a Shear-Lag Model With Cohesive Zone. IEEE Transactions on Device and Materials Reliability, 2014, 14, 318-326.	1.5	23
59	Interfacial adhesion between graphene and silicon dioxide by density functional theory with van der Waals corrections. Journal Physics D: Applied Physics, 2014, 47, 255301.	1.3	109
60	Nonlinear analysis of compressed elastic thin films on elastic substrates: From wrinkling to buckle-delamination. International Journal of Solids and Structures, 2014, 51, 3715-3726.	1.3	64
61	Thermomechanics of monolayer graphene: Rippling, thermal expansion and elasticity. Journal of the Mechanics and Physics of Solids, 2014, 66, 42-58.	2.3	138
62	Stretch-induced wrinkling of polyethylene thin sheets: Experiments and modeling. International Journal of Solids and Structures, 2014, 51, 1847-1858.	1.3	52
63	A blister test for interfacial adhesion of large-scale transferred graphene. Carbon, 2014, 69, 390-400.	5.4	88
64	Thermal Stress in 3-D Packaging. , 2014, , 5208-5217.		0
65	Impact of Grain Structure and Material Properties on Via Extrusion in 3-D Interconnects. International Symposium on Microelectronics, 2014, 2014, 000008-000012.	0.3	0
66	Creases and wrinkles on the surface of a swollen gel. Journal of Applied Physics, 2013, 114, .	1.1	46
67	Characterization of plasticity and stresses in TSV structures in stacked dies using synchrotron x-ray microdiffraction. , 2013, , .		5
68	Swell-induced surface instability of hydrogel layers with material properties varying in thickness direction. International Journal of Solids and Structures, 2013, 50, 578-587.	1.3	73
69	Measurement and analysis of thermal stresses in 3D integrated structures containing through-silicon-vias. Microelectronics Reliability, 2013, 53, 53-62.	0.9	96
70	Numerical Analysis of Circular Graphene Bubbles. Journal of Applied Mechanics, Transactions ASME, 2013, 80, .	1.1	60
71	Impact of material and microstructure on thermal stresses and reliability of through-silicon via (TSV) structures. , 2013, , .		5
72	Plasticity mechanism for copper extrusion in through-silicon vias for three-dimensional interconnects. Applied Physics Letters, 2013, 103, .	1.5	57

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73	A Kinetics Approach to Surface Wrinkling of Elastic Thin Films. , 2013, , 69-109.		2
74	Characterization of thermal stresses in through-silicon vias for three-dimensional interconnects by bending beam technique. Applied Physics Letters, 2012, 100, 041901.	1.5	96
75	Micro-Raman spectroscopy and analysis of near-surface stresses in silicon around through-silicon vias for three-dimensional interconnects. Journal of Applied Physics, 2012, 111, .	1.1	94
76	Measurement and analysis of thermal stresses in 3-D integrated structures containing through-silicon vias. , 2012, , .		3
77	Thermal stress characteristics and reliability impact on 3-D ICs containing through-silicon vias. , 2012, , .		1
78	A comparison of direct and iterative methods for determining traction-separation relations. International Journal of Fracture, 2012, 177, 109-128.	1.1	50
79	Effect of Thermal Stresses on Carrier Mobility and Keep-Out Zone Around Through-Silicon Vias for 3-D Integration. IEEE Transactions on Device and Materials Reliability, 2012, 12, 255-262.	1.5	106
80	Thermal stress characteristics and impact on device keep-out zone for 3-D ICs containing through-silicon vias. , 2012, , .		2
81	Unique Aspects of a Shape Memory Polymer As the Substrate for Surface Wrinkling. ACS Applied Materials & Interfaces, 2012, 4, 598-603.	4.0	62
82	Dielectric elastomer actuators under equal-biaxial forces, uniaxial forces, and uniaxial constraint of stiff fibers. Soft Matter, 2012, 8, 6167.	1.2	237
83	Anisotropic, Hierarchical Surface Patterns via Surface Wrinkling of Nanopatterned Polymer Films. Nano Letters, 2012, 12, 5995-5999.	4.5	88
84	Electromechanical phase transition in dielectric elastomers. Proceedings of the Royal Society A: Mathematical, Physical and Engineering Sciences, 2012, 468, 1014-1040.	1.0	69
85	Analytical methods for the mechanics of graphene bubbles. Journal of Applied Physics, 2012, 112, .	1.1	99
86	Swelling kinetics of polymer gels: comparison of linear and nonlinear theories. Soft Matter, 2012, 8, 8194.	1.2	146
87	Path-€ Guided Wrinkling of Nanoscale Metal Films. Advanced Materials, 2012, 24, 3010-3014.	11.1	57
88	Impact of Near-Surface Thermal Stresses on Interfacial Reliability of Through-Silicon Vias for 3-D Interconnects. IEEE Transactions on Device and Materials Reliability, 2011, 11, 35-43.	1.5	228
89	A fast simulation framework for full-chip thermo-mechanical stress and reliability analysis of through-silicon-via based 3D ICs. , 2011, , .		11
90	Effect of surface roughness on adhesion of graphene membranes. Journal Physics D: Applied Physics, 2011, 44, 452001.	1.3	100

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91	Swelling behavior of nanoscale, shape- and size-specific, hydrogel particles fabricated using imprint lithography. <i>Soft Matter</i> , 2011, 7, 2879.	1.2	49
92	Show of adhesive strength. <i>Nature Nanotechnology</i> , 2011, 6, 537-538.	15.6	41
93	Nonlinear Mechanical Properties of Graphene Nanoribbons. <i>Materials Research Society Symposia Proceedings</i> , 2011, 1284, 165.	0.1	1
94	Atomistic simulation and continuum modeling of graphene nanoribbons under uniaxial tension. <i>Modelling and Simulation in Materials Science and Engineering</i> , 2011, 19, 054006.	0.8	121
95	Stress-Induced Delamination Of Through Silicon Via Structures. <i>AIP Conference Proceedings</i> , 2011, , .	0.3	14
96	Concomitant wrinkling and buckle-delamination of elastic thin films on compliant substrates. <i>Mechanics of Materials</i> , 2011, 43, 627-642.	1.7	159
97	Stretch-induced stress patterns and wrinkles in hyperelastic thin sheets. <i>International Journal of Solids and Structures</i> , 2011, 48, 3471-3483.	1.3	109
98	Thermomechanical reliability of through-silicon vias in 3D interconnects. , 2011, , .		20
99	Temperature-dependent thermal stress determination for through-silicon vias (TSVs) by combining bending beam technique with finite element analysis. , 2011, , .		10
100	SWELLING-INDUCED INSTABILITY OF SUBSTRATE-ATTACHED HYDROGEL LINES. <i>International Journal of Applied Mechanics</i> , 2011, 03, 219-233.	1.3	32
101	“Mechanical Behavior of Nanostructured Materials” <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2010, 41, 777-777.	1.1	1
102	Swell-induced surface instability of confined hydrogel layers on substrates. <i>Journal of the Mechanics and Physics of Solids</i> , 2010, 58, 1582-1598.	2.3	100
103	Thermomechanical Reliability Challenges For 3D Interconnects With Through-Silicon Vias. <i>AIP Conference Proceedings</i> , 2010, , .	0.3	10
104	Initiation and propagation of interfacial delamination in integrated thin-film structures. , 2010, , .		13
105	Disparate tendency of stress evolution of thin and thick electroplated Cu films at room temperature. , 2010, , .		1
106	A Variational Approach and Finite Element Implementation for Swelling of Polymeric Hydrogels Under Geometric Constraints. <i>Journal of Applied Mechanics, Transactions ASME</i> , 2010, 77, .	1.1	86
107	Interfacial Delamination Between Through Silicon Vias (TSVs) and Silicon Matrix. , 2010, , .		3
108	Effects of mismatch strain and substrate surface corrugation on morphology of supported monolayer graphene. <i>Journal of Applied Physics</i> , 2010, 107, .	1.1	136

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109	Two-Dimensional Phonon Transport in Supported Graphene. <i>Science</i> , 2010, 328, 213-216.	6.0	1,692
110	Effect of surface tension on swell-induced surface instability of substrate-confined hydrogel layers. <i>Soft Matter</i> , 2010, 6, 5736.	1.2	38
111	Excess energy and deformation along free edges of graphene nanoribbons. <i>Physical Review B</i> , 2010, 81, .	1.1	78
112	Thermal stress induced delamination of through silicon vias in 3-D interconnects. , 2010, , .		85
113	Indentation of single-crystal silicon nanolines: Buckling and contact friction at nanoscales. <i>Journal of Applied Physics</i> , 2009, 105, 073510.	1.1	1
114	Effect of elastic anisotropy on surface pattern evolution of epitaxial thin films. <i>International Journal of Solids and Structures</i> , 2009, 46, 2822-2833.	1.3	13
115	NONLINEAR MECHANICS OF SINGLE-ATOMIC-LAYER GRAPHENE SHEETS. <i>International Journal of Applied Mechanics</i> , 2009, 01, 443-467.	1.3	222
116	Elastic bending modulus of monolayer graphene. <i>Journal Physics D: Applied Physics</i> , 2009, 42, 102002.	1.3	326
117	Thermo-mechanical reliability of 3-D ICs containing through silicon vias. , 2009, , .		158
118	Viscoelastic properties of confined polymer films measured via thermal wrinkling. <i>Soft Matter</i> , 2009, 5, 4638.	1.2	61
119	Nanoindentation of Si Nanostructures: Buckling and Friction at Nanoscales. , 2009, , .		1
120	Thermal Stresses Analysis of 3-D Interconnect. , 2009, , .		16
121	Internal lattice relaxation of single-layer graphene under in-plane deformation. <i>Journal of the Mechanics and Physics of Solids</i> , 2008, 56, 1609-1623.	2.3	164
122	Wrinkle patterns of anisotropic crystal films on viscoelastic substrates. <i>Journal of the Mechanics and Physics of Solids</i> , 2008, 56, 3315-3330.	2.3	73
123	Fracture, delamination, and buckling of elastic thin films on compliant substrates. <i>Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems</i> , 2008, , .	0.0	1
124	Fabrication and Characterization of Patterned Single-Crystal Silicon Nanolines. <i>Nano Letters</i> , 2008, 8, 92-98.	4.5	28
125	Mechanical Characterization of High Aspect Ratio Silicon Nanolines. <i>Materials Research Society Symposia Proceedings</i> , 2008, 1086, 1.	0.1	0
126	Buckling of Single-Crystal Silicon Nanolines under Indentation. <i>Journal of Nanomaterials</i> , 2008, 2008, 1-11.	1.5	3

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127	Impact of Process Induced Stresses and Chip-Packaging Interaction on Reliability of Air-gap Interconnects. , 2008, , .		9
128	Buckling modes of elastic thin films on elastic substrates. Applied Physics Letters, 2007, 90, 151902.	1.5	179
129	Bifurcation of surface pattern in epitaxial thin films under anisotropic stresses. Journal of Applied Physics, 2007, 101, 023519.	1.1	8
130	Effect of Surface Properties on Wrinkling of Ultrathin Films. Journal of Aerospace Engineering, 2007, 20, 38-44.	0.8	63
131	Influence of Interfacial Delamination on Channel Cracking of Brittle Thin Films. Materials Research Society Symposia Proceedings, 2007, 990, 1.	0.1	1
132	Finite element modeling of stress variation in multilayer thin-film specimens for in situ transmission electron microscopy experiments. Journal of Materials Research, 2007, 22, 2737-2741.	1.2	3
133	Influence of interfacial delamination on channel cracking of elastic thin films. International Journal of Fracture, 2007, 148, 331-342.	1.1	52
134	Dynamics of wrinkle growth and coarsening in stressed thin films. Physical Review E, 2006, 74, 026214.	0.8	98
135	Trapped Torsional Vibrations in Elastic Plates. , 2006, , .		0
136	Energy-Trapping Torsional-Mode Resonators for Liquid Sensing. , 2006, , .		4
137	Elastic Moduli of Ultrathin Amorphous Polymer Films. Macromolecules, 2006, 39, 5095-5099.	2.2	389
138	Nonlinear effect of stress and wetting on surface evolution of epitaxial thin films. Physical Review B, 2006, 74, .	1.1	61
139	Torsional vibrations of circular elastic plates with thickness steps. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2006, 53, 349-359.	1.7	10
140	Effect of passivation on stress relaxation in electroplated copper films. Journal of Materials Research, 2006, 21, 1512-1518.	1.2	44
141	Wrinkling of Ultrathin Polymer Films. Materials Research Society Symposia Proceedings, 2006, 924, 1.	0.1	4
142	Pattern Evolution of Self-Assembled Quantum Dots Under Biaxial Stresses. Materials Research Society Symposia Proceedings, 2006, 921, 1.	0.1	0
143	Kinetic wrinkling of an elastic film on a viscoelastic substrate. Journal of the Mechanics and Physics of Solids, 2005, 53, 63-89.	2.3	280
144	Isothermal stress relaxation in electroplated Cu films. II. Kinetic modeling. Journal of Applied Physics, 2005, 97, 103532.	1.1	33

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145	Electrically induced surface instability of a conductive thin film on a dielectric substrate. Applied Physics Letters, 2005, 87, 151911.	1.5	12
146	Effect of a cap layer on morphological stability of a strained epitaxial film. Journal of Applied Physics, 2005, 97, 113537.	1.1	6
147	Isothermal stress relaxation in electroplated Cu films. I. Mass transport measurements. Journal of Applied Physics, 2005, 97, 103531.	1.1	70
148	Trapped torsional vibrations in elastic plates. Applied Physics Letters, 2005, 87, 201911.	1.5	6
149	Effects of Passivation Layer on Stress Relaxation and Mass Transport in Electroplated Cu Films. AIP Conference Proceedings, 2004, . .	0.3	5
150	Modeling quasi-static crack growth with the extended finite element method Part II: Numerical applications. International Journal of Solids and Structures, 2003, 40, 7539-7552.	1.3	143
151	Channel-cracking of thin films with the extended finite element method. Engineering Fracture Mechanics, 2003, 70, 2513-2526.	2.0	108
152	Evolving crack patterns in thin films with the extended finite element method. International Journal of Solids and Structures, 2003, 40, 2343-2354.	1.3	64
153	Very thin solid-on-liquid structures: the interplay of flexural rigidity, membrane force, and interfacial force. Thin Solid Films, 2003, 429, 273-281.	0.8	27
154	Buckling suppression of SiGe islands on compliant substrates. Journal of Applied Physics, 2003, 94, 6875-6882.	1.1	32
155	Morphological Instability of Solid-on-Liquid Thin Film Structures. Materials Research Society Symposia Proceedings, 2002, 749, 1.	0.1	0
156	Effects of a liquid layer on thickness-shear vibrations of rectangular AT-cut quartz plates. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2002, 49, 604-611.	1.7	20
157	Wrinkling of a compressed elastic film on a viscous layer. Journal of Applied Physics, 2002, 91, 1135-1142.	1.1	223
158	Mechanical effects of electrodes on the vibrations of quartz crystal plates. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2002, 49, 612-625.	1.7	16
159	Extensional, thickness-stretch and symmetric thickness-shear vibrations of piezoceramic disks. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2002, 49, 1507-1515.	1.7	25
160	Strain relaxation of SiGe islands on compliant oxide. Journal of Applied Physics, 2002, 91, 9716.	1.1	70
161	Mechanics of relaxing SiGe islands on a viscous glass. Acta Mechanica Sinica/Lixue Xuebao, 2002, 18, 441-456.	1.5	9
162	Relaxation of compressed elastic islands on a viscous layer. Acta Materialia, 2002, 50, 2933-2944.	3.8	41

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163	Inhomogeneous deformation in metallic glasses. <i>Journal of the Mechanics and Physics of Solids</i> , 2002, 50, 1011-1027.	2.3	220
164	Loss of constraint on fracture in thin film structures due to creep. <i>Acta Materialia</i> , 2002, 50, 4137-4148.	3.8	42
165	Instability of a compressed elastic film on a viscous layer. <i>International Journal of Solids and Structures</i> , 2002, 39, 1791-1802.	1.3	108
166	Vibrations and static responses of asymmetric bimorph disks of piezoelectric ceramics. <i>IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control</i> , 2000, 47, 706-715.	1.7	21